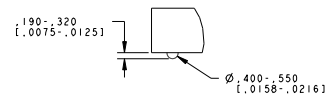
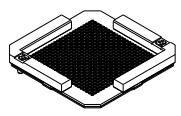
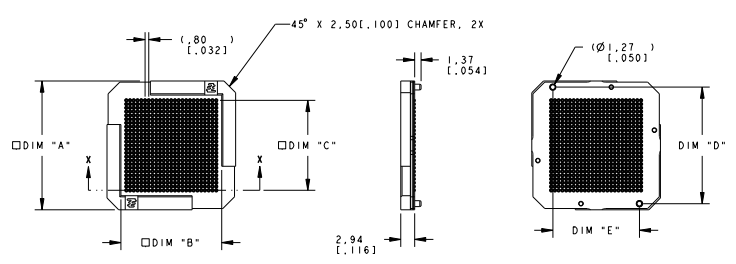


MATRIX BGA SOCKET TYPE 1 ( 0.8 MM )								
PART NO.	NO. OF CONTACTS	GRID	DIM A	DIM B	DIM C	DIM D	DIM E	LOAD
1640294-4	324	18X18	21.50 [.8463]	15.50 [.6101]	13.50 [.5315]	18.40 [.7244]	12.50 [.4921]	32±8 LBS
1640294-5	361	19X19	25.50 [.9991]	18.50 [.7283]	14.50 [.5707]	19.50 [.7677]	13.50 [.5311]	36±9 LBS
1640294-6	400	20X20	25.50 [.9991]	17.50 [.6889]	15.50 [.6101]	19.50 [.7677]	14.50 [.5707]	40±10 LBS
1640294-7	484	22X22	24.50 [.9645]	17.50 [.6889]	16.00 [.6299]	20.50 [.8071]	15.50 [.6101]	48±12 LBS
1640294-8	529	23X23	25.50 [.9991]	19.50 [.7677]	17.00 [.6693]	20.50 [.8071]	16.50 [.6495]	52±13 LBS
1640294-9	576	24X24	26.50 [1.0433]	20.50 [.8071]	18.40 [.7244]	23.50 [.9251]	17.50 [.6889]	57±14 LBS
1-1640294-0	625	25X25	27.50 [1.0827]	21.50 [.8463]	19.20 [.7560]	24.50 [.9645]	18.50 [.7283]	62±16 LBS
1-1640294-4	324	18X18	22.50 [.8861]	16.50 [.6495]	13.50 [.5311]	18.50 [.7283]	13.50 [.5311]	32±8 LBS
1-1640294-5	361	19X19	24.50 [.9645]	17.50 [.6889]	14.50 [.5707]	19.50 [.7677]	14.50 [.5707]	36±9 LBS
1-1640294-6	441	21X21	24.50 [.9645]	18.50 [.7283]	14.50 [.5707]	20.50 [.8071]	15.50 [.6101]	44±11 LBS
1-1640294-7	484	22X22	25.50 [.9991]	18.50 [.7283]	16.00 [.6299]	20.50 [.8071]	16.50 [.6495]	48±12 LBS
1-1640294-8	529	23X23	26.50 [1.0433]	20.50 [.8071]	17.00 [.6693]	23.50 [.9251]	17.50 [.6889]	52±13 LBS
1-1640294-9	576	24X24	27.50 [1.0827]	21.50 [.8463]	18.40 [.7244]	24.50 [.9645]	18.50 [.7283]	57±14 LBS



TYPE 1 BGA PACKAGE SPEC  
SCALE = 10X

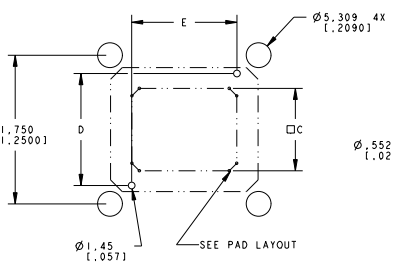
**SPECIFICATIONS:**

**MATERIALS:**  
CONDUCTIVE COLUMN: HXC-125.  
INSULATOR: POLYIMIDE.  
FRAME: 94V-0 ULTEM.

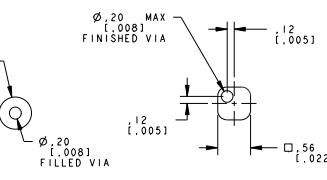
**MECHANICAL:**  
MPI TOTAL LOAD: SEE CHART

**APPLICATION:**  
THIS SOCKET IS DESIGNED FOR COMPRESSION MOUNT.  
FOR MORE INFORMATION REFERENCE MPI APPLICATION GUIDE,  
P/N 1640905 (BGA).

PRELIMINARY



PCB FOOTPRINT



RECOMMENDED PCB PADS  
SCALE = 25X

- NOTES:** UNLESS OTHERWISE SPECIFIED
1. INTERPRET DRAWING PER ASME Y14.5M-1994.
  2. DOES NOT INCLUDE VESTIGE OR SURFACE ENRICHMENT.
  3. THE SOLDER MASK ON THE PCB ARRAY MUST BE NO MORE THAN 15 MICRO METERS THICK.
  4. STANDARD CHEMICAL GOLD PLATING IS ACCEPTABLE FOR PCB FAB IN THE USE OF THIS SOCKET.
  5. RoHS COMPLIANT AND CERTIFIED.

1	PRELIMINARY	1	PRELIMINARY
2	PRELIMINARY	2	PRELIMINARY
3	PRELIMINARY	3	PRELIMINARY
4	PRELIMINARY	4	PRELIMINARY
5	PRELIMINARY	5	PRELIMINARY
6	PRELIMINARY	6	PRELIMINARY

<b>Tyco Electronics</b>		Norwood, Massachusetts 01962		<b>CUSTOMER DRAWING</b>	
DESIGNER: D. AMARAL	DATE: 1-2-03	MATERIAL: N/A	REV: 1	TITLE: SOCKET ASSEMBLY	
ENGINEER: WA	DATE: 1-20-03	PRINTED: N/A	REV: 1	PART NO.: 1640294	
ILLUSTRATOR: PROTEC SYSTEMS	DATE: N/A	SCALE: N/A	REV: 1	TYPE: 1	
APPROVED: N/A	DATE: N/A	SCALE: N/A	REV: 1	SHEET NO.: 6	
ANGLES: 45°	SCALE: N/A	SCALE: N/A	REV: 1	C-1640294	